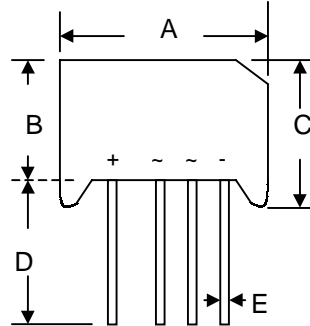
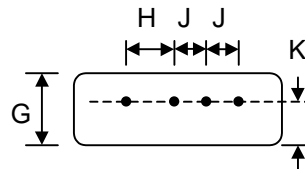


### Features

- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards



RS-5		
Dim	Min	Max
A	39.40	40.10
B	20.20	21.00
C	21.00	21.70
D	25.40	—
E	0.97 Ø	1.07 Ø
G	6.20	6.70
H	9.80	10.20
J	7.20	7.60
K	4.60	5.00
All Dimensions in mm		



### Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 25.3 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	B40C3700/ 2200	B80C3700/ 2200	B125C3700/ 2200	B250C3700/ 2200	B380C3700/ 2200	Unit	
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>						V	
Working Peak Reverse Voltage	V <sub>RWM</sub>	100	200	300	600	900		
DC Blocking Voltage	V <sub>R</sub>							
Recommend Input Voltage	V <sub>RMS</sub>	40	80	125	250	380	V	
Average Rectified Output Current @T <sub>A</sub> = 45°C (Note 1)	I <sub>O</sub>	3.7						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	100						A
Repetitive Peak Forward Surge Current	I <sub>FRM</sub>	15						A
Forward Voltage (per element) @I <sub>F</sub> = 3.0A	V <sub>FM</sub>	1.0						V
Peak Reverse Current @T <sub>C</sub> = 25°C At Rated DC Blocking Voltage @T <sub>C</sub> = 150°C	I <sub>R</sub>	10 6.0						µA mA
Rating for Fusing (t < 8.3ms) (Note 2)	I <sub>t</sub> <sup>2</sup>	50						A <sup>2</sup> s
Typical Thermal Resistance (Note 1)	R <sub>θJA</sub>	3.0						K/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +150						°C

**\*Glass Passivated forms are available upon request.**

Note: 1. Measured at 3"sq. x 0.11" thick AL. plate.  
2. Non-repetitive for t > 1ms and < 8.3ms.

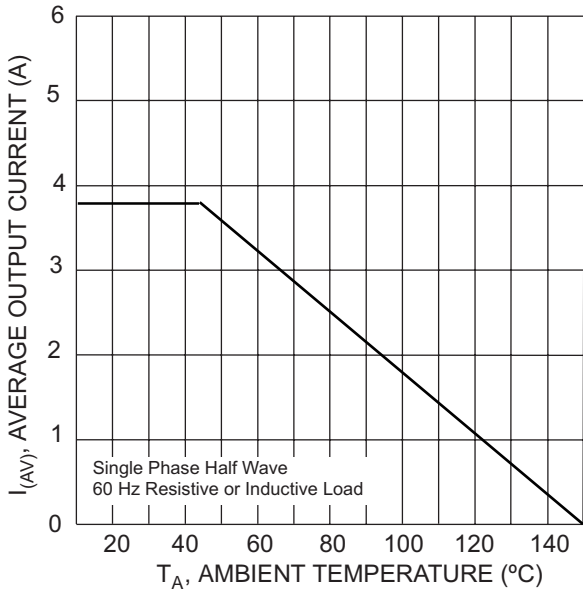


Fig. 1 Forward Current Derating Curve

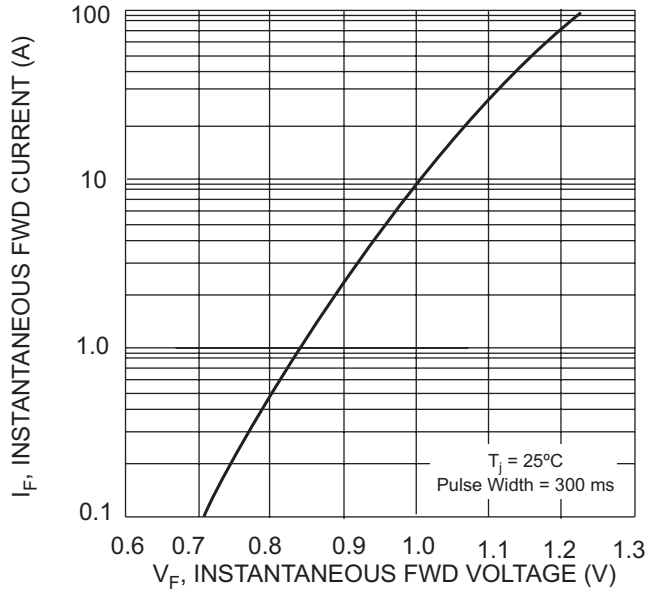


Fig. 2 Typical Forward Characteristics, per element

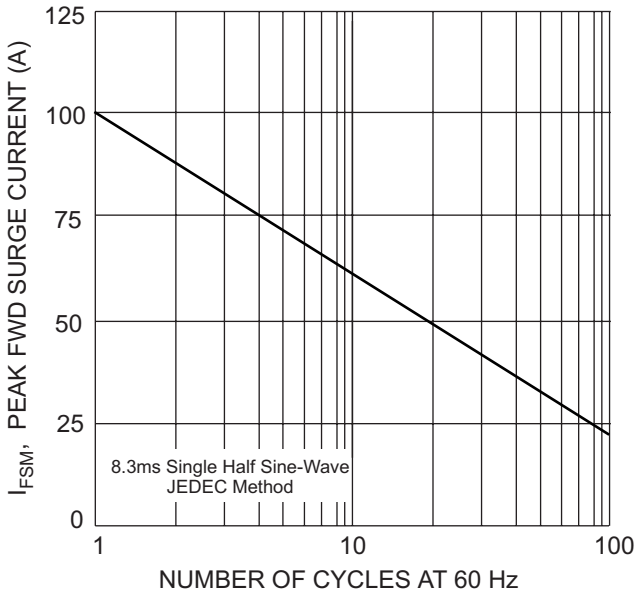


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

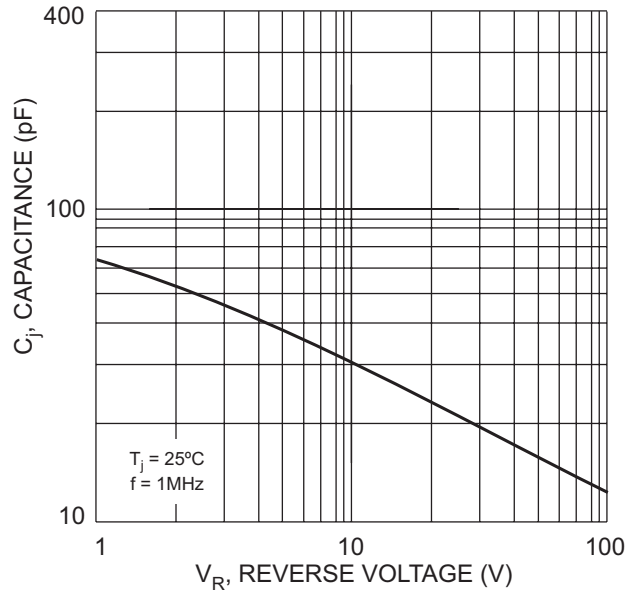


Fig. 4 Typical Junction Capacitance Per Element



Fig. 5 Typical Reverse Characteristics

## ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
B40C3700/2200	SIL Bridge	200 Units/Box
B80C3700/2200	SIL Bridge	200 Units/Box
B125C3700/2200	SIL Bridge	200 Units/Box
B250C3700/2200	SIL Bridge	200 Units/Box
B380C3700/2200	SIL Bridge	200 Units/Box

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

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**Won-Top Electronics Co., Ltd.**

No. 44 Yu Kang North 3rd Road, Chine Chen Dist., Kaohsiung, Taiwan

**Phone:** 886-7-822-5408 or 886-7-822-5410

**Fax:** 886-7-822-5417

**Email:** sales@wontop.com

**Internet:** <http://www.wontop.com>

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